NGUYEN HUU ANH

SOFTWARE ENGINEER – BACHELOR DEGREE – HCMC INDUSTRY AND TRADE COLLEGE

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**About Me** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

I have over 4 years of experience in software development for semiconductor equipment (Wire Bonder UTC-3000, UTC-5000, UTC-5100 and Bump Bonder SBB-5200).

Strong knowledge about C, C++, MFC Framework and OOP programming.

Additional programming with CSharp, VB.NET, Auto LISP, Python.

Familiar with Visual Studio, Team Foundation Server (TFS), Github, Visual SourceSafe, IBM Lotus Notes.

Ability to writing and reading English documents.

**Experience** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**SHINKAWA VIETNAM CO., LTD**

**Junior Software Engineer** **– R&D TEAM** *Mar. 2019 to Oct. 2020*

**Software Engineer – DESIGN TEAM** *Nov. 2016 to Mar. 2019*

**Education** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**HCMC INDUSTRY AND TRADE COLLEGE** – Bachelor Degree. *Oct. 2012 – Mar. 2016*

**Specialty** – Information Technology.